

Development of a nanoscale linewidth-standard for high-resolution optical microscopy



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Goal

Development of a traceable linewidth/pitch-standard on the nanometre scale for use in new kinds of high resolution light-microscopy

- DUV and UV microscopy (UVM, DUVM),
- Confocal laser-scanning microscopy (CLSM)

Realisation



Ion-beam sputtering

- Deposition of amorphous silicon film onto a quartz wafer

Electron beam lithography (LION LV1)

- Resist: 120 nm ARP671 (PMMMA)

Dry etch of the silicon pattern

- Electron cyclotron resonance (ECR) high-density plasma with CHF_3

Testing

Different user specific measurement and microscopy tools:

• SEM JEOL JSM 6700F

• CD-SEM LEO Supra 35 VP

• UV-microscope Leica INM 200 ($\lambda = 365 \text{ nm}$, $\text{NA} = 0.9$)

• UV-microscope Leica INM 300 DUV ($\lambda = 248 \text{ nm}$, $\text{NA} = 0.8$ dry and $\text{NA} = 1.2$ immersion)

• LSM 5 PASCAL ($\lambda = 405 \text{ nm}$, $\text{NA} = 0.95$)

• FRT MicroGlider[®] with CWL optical sensor and AFM

Calibration

- PTB Braunschweig
- Leica DKD-Calibration Laboratory, Jena

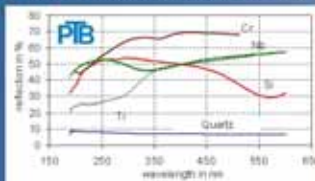
Results

Si gratings on quartz substrates as prototype of a nanoscale CD-standard with pitch structures down to 160 nm, have been fabricated and initially evaluated using state-of-the-art UVM, CLSM, SEM and AFM equipment.

- Quick every day tests of the optical tool.
- Lateral x-y-resolution and CD (critical dimension),
- State of the optical system (e.g. astigmatism),
- Upgrade of the microscope to a measurement tool,
- Additional potential for calibration of AFM-tools and scanning electron microscopes (SEM)

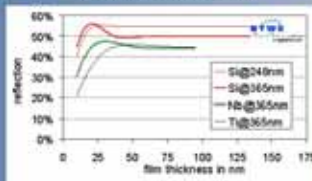
Choice of material → amorphous Si on quartz

Investigations of different materials



Measured spectral reflectance of different thin film materials, with quartz as reference.

Thickness dependence



Dependence of reflection vs. film thickness (simulation)

Contrast "Si on quartz" vs. wavelength



Obtained ratio of reflectance of a 45 nm thick amorphous Si thin film on quartz vs. wavelength.

Description and characterisation of the high resolution patterns

1-dim line-grating pitch 160 nm, etched in 50 nm thick Si on quartz. An isolated single structure for CD determination is added (80 nm).

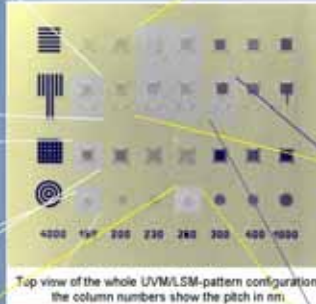
2-dim (cross grating) with a period of 160 nm

Period: 130 nm (resist mask)
 Period: 160 nm (etched into Si on quartz)
 SEM-pictures show centre part of circular gratings

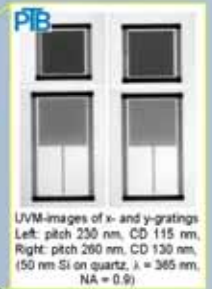
Calibration structure

Gratings: 1-dim (for both x and y), 2-dim (cross grating) and circular.
 An isolated single structure for CD-determination is added to one side of the 1-dim grating.

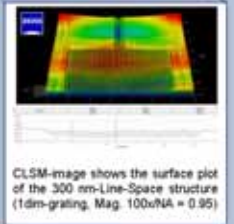
Line width: 80 nm to 2000 nm
 Pitch: 160 nm to 4000 nm
 Material: Si (amorphous) on quartz
 Thickness: 30 to 50 nm



Top view of the whole UVM/LSM-pattern configuration, the column numbers show the pitch in nm



UVM-images of x- and y-gratings
 Left: pitch 230 nm, CD 115 nm,
 Right: pitch 260 nm, CD 130 nm,
 (50 nm Si on quartz, $\lambda = 365 \text{ nm}$,
 $\text{NA} = 0.9$)



CLSM-image shows the surface plot of the 300 nm-Line-Space structure (1dim-grating, Mag. 100xNA = 0.95)

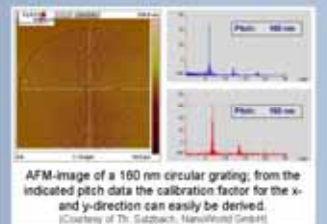
APPLICABILITY in SEM, DUVM and AFM



SEM-Picture of the centre part of the 160 nm circular grating etched into Si on quartz



DUVM-images of the 160 nm circular grating (Si on quartz) made by dry-objective (left, $\text{NA} = 0.8$) and immersion-objective (right, $\text{NA} = 1.2$) (Courtesy of W. Volkath, Leica Microsystems AG)



AFM-image of a 160 nm circular grating, from the indicated pitch data the calibration factor for the x- and y-direction can easily be derived. (Courtesy of Th. Gatzbach, NanoWorld GmbH)